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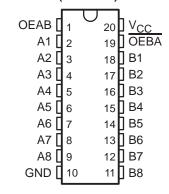
- State-of-the-Art *EPIC-IIB™* BiCMOS Design Significantly Reduces Power Dissipation
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per **JESD 17**
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$
- High-Drive Outputs (-32-mA IOH, 64-mA IOI)
- **Package Options Include Plastic** Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), and Plastic (N) and Ceramic (J) DIPs

description

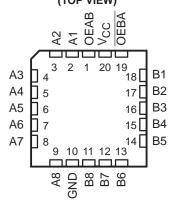
These octal bus transceivers provide for asynchronous communication between data buses. The control-function implementation allows for maximum flexibility in timing. The 'ABT620 devices provide inverted data at the outputs.

These devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic levels at the output-enable (OEAB and OEBA) inputs.

SN54ABT620 . . . J PACKAGE SN74ABT620...DB, DW, N, OR PW PACKAGE (TOP VIEW)



SN54ABT620 . . . FK PACKAGE (TOP VIEW)



The output-enable inputs can be used to disable the device so that the buses are effectively isolated. The dual-enable configuration gives the transceivers the capability of storing data by simultaneously enabling OEAB and OEBA. When both OEAB and OEBA are enabled and all other data sources to the two sets of bus lines are at high impedance, both sets of bus lines (16 total) remain at their last states. In this way, each output reinforces its input in this configuration.

To ensure the high-impedance state during power up or power down, OEBA should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

The SN54ABT620 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT620 is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

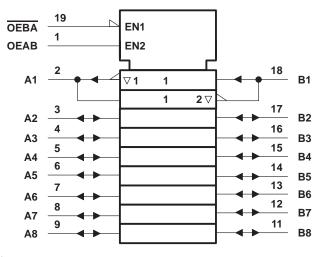
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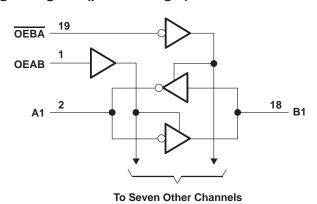
FUNCTION TABLE

| INP | UTS | OPERATION |
|------|------|-------------------------------------|
| OEBA | OEAB | OPERATION |
| L | L | B data to A bus |
| L | Н | B data to A bus, A data to B bus |
| Н | L | Isolation |
| Н | Н | A data to B bus |

logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

| Supply voltage range, V _{CC} | |
|--|---|
| Input voltage range, V _I (see Note 1) | –0.5 V to 7 V |
| Voltage range applied to any output in the high or | power-off state, V _O –0.5 V to 5.5 V |
| Current into any output in the low state, IO: SN54 | 4ABT620 96 mA |
| SN74 | 4ABT620 128 mA |
| Input clamp current, I _{IK} (V _I < 0) | |
| Output clamp current, I _{OK} (V _O < 0) | |
| Package thermal impedance, θ _{JA} (see Note 2): D | DB package 115°C/W |
| D | DW package 97°C/W |
| N | I package 67°C/W |
| P | PW package 128°C/W |
| Storage temperature range, T _{stq} | |

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.



^{2.} The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

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recommended operating conditions (see Note 3)

| | | | SN54A | BT620 | SN74A | BT620 | UNIT |
|-------|------------------------------------|-----------------|-------------|-------|-------|-------|------|
| | | | MIN | MAX | MIN | MAX | UNIT |
| VCC | Supply voltage | | 4.5 | 5.5 | 4.5 | 5.5 | V |
| VIH | High-level input voltage | | 2 | EW | 2 | | V |
| VIL | Low-level input voltage | | | 0.8 | | 0.8 | V |
| VI | Input voltage | | 0 < | Vcc | 0 | VCC | V |
| IOH | High-level output current | | , () | -24 | | -32 | mA |
| loL | Low-level output current | | 200 | 48 | | 64 | mA |
| Δt/Δν | Input transition rise or fall rate | Outputs enabled | A. | 5 | | 5 | ns/V |
| TA | Operating free-air temperature | | <i>–</i> 55 | 125 | -40 | 85 | °C |

NOTE 3: All unused pins (control or I/O) of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN54ABT620, SN74ABT620 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| DAI | DAMETED | TEST CON | IDITIONS | Т | A = 25°C | ; | SN54A | BT620 | SN74A | BT620 | UNIT | |
|--------------------|----------------|--|----------------------------------|-----|----------|-------|-------------|-------------|-------|-------|------|--|
| PAI | RAMETER | TEST CON | CMOITIUIS | MIN | TYP† | MAX | MIN | MAX | MIN | MAX | UNII | |
| VIK | | V _{CC} = 4.5 V, | I _I = -18 mA | | | -1.2 | | -1.2 | | -1.2 | V | |
| | | $V_{CC} = 4.5 \text{ V},$ | $I_{OH} = -3 \text{ mA}$ | 2.5 | | | 2.5 | | 2.5 | | | |
| \/~ | | $V_{CC} = 5 V$, | $I_{OH} = -3 \text{ mA}$ | 3 | | | 3 | | 3 | | v | |
| VOH | | V _{CC} = 4.5 V | $I_{OH} = -24 \text{ mA}$ | 2 | | | 2 | | | | V | |
| | | VCC = 4.5 V | $I_{OH} = -32 \text{ mA}$ | 2* | | | | | 2 | | | |
| VOL | | V _{CC} = 4.5 V | I _{OL} = 48 mA | | | 0.55 | | 0.55 | | | V | |
| VOL | | VCC = 4.5 V | I _{OL} = 64 mA | | | 0.55* | | | | 0.55 | v | |
| V _{hys} | | | | | 100 | | | | | | mV | |
| | Control inputs | V _{CC} = 5.5 V, | VI = VCC or GND | | | ±1 | | ±1 | | ±1 | μΑ | |
| H | A or B ports | | AL = ACC OLGIAD | | | ±100 | | ±100 | | ±100 | μΑ | |
| lozh [‡] | | $V_{CC} = 5.5 \text{ V},$ | V _O = 2.7 V | | | 50 | | 50 | | 50 | μΑ | |
| l _{OZL} ‡ | | $V_{CC} = 5.5 \text{ V},$ | V _O = 0.5 V | | | -50 | | – 50 | | -50 | μΑ | |
| I _{off} | | $V_{CC} = 0$, | V_I or $V_O \le 4.5 \text{ V}$ | | | ±100 | 1 | ζ | | ±100 | μΑ | |
| ICEX | | V _{CC} = 5.5 V, V _O = 5.5 V | Outputs high | | | 50 | 2700 | 50 | | 50 | μΑ | |
| IO§ | | V _{CC} = 5.5 V, | V _O = 2.5 V | -50 | -100 | -180 | – 50 | -180 | -50 | -180 | mA | |
| | | V _{CC} = 5.5 V, | Outputs high | | 5 | 250 | | 250 | | 250 | μΑ | |
| Icc | A or B ports | $I_0 = 0$, | Outputs low | | 24 | 30 | | 30 | | 30 | mA | |
| | | $V_I = V_{CC}$ or GND | Outputs disabled | | 0.5 | 250 | | 250 | | 250 | μΑ | |
| | Doto inputo | V _{CC} = 5.5 V, One input at 3.4 V, | Outputs enabled | | | 1.5 | | 1.5 | | 1.5 | | |
| ΔICC¶ | Data inputs | Other inputs at V _{CC} or GND | Outputs disabled | | | 0.05 | | 0.05 | | 0.05 | mA | |
| | Control inputs | $V_{CC} = 5.5 \text{ V}$, One inpute of the original of the contraction o | | | | 1.5 | | 1.5 | | 1.5 | | |
| Ci | Control inputs | V _I = 2.5 V or 0.5 V | | | 4 | | | | | | pF | |
| C _{io} | A or B ports | V _O = 2.5 V or 0.5 V | | | 7 | | | | | | pF | |

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] The parameters I_{OZH} and I_{OZL} include the input leakage current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

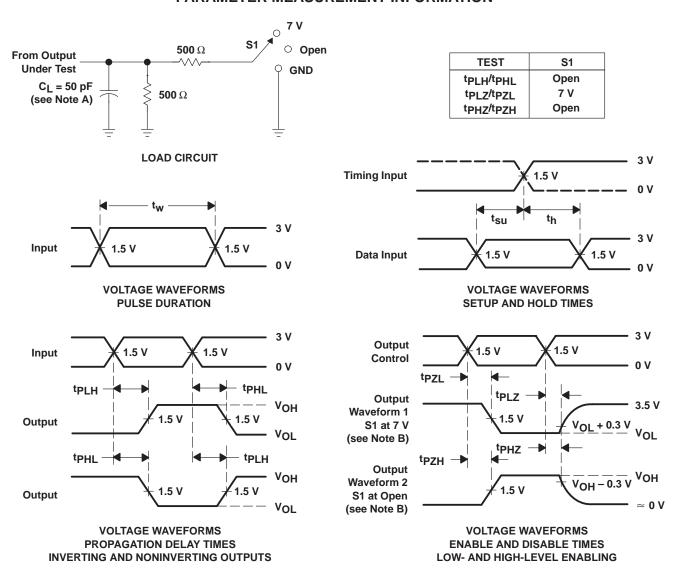
[¶] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V _{CC} = 5 V, T _A = 25°C | | SN54ABT620 | | SN74A | UNIT | |
|------------------|-----------------|----------------|---|-----|-------------|-----|-------|------|-----|
| | (IIVI O1) | (0011 01) | MIN | MAX | MIN | MAX | MIN | MAX | |
| ^t PLH | A or B | B or A | 1 | 4.1 | 1 | | 1 | 4.8 | |
| ^t PHL | AOIB | D OF A | 1 | 4.3 | 1 | 4 | 1 | 4.8 | ns |
| ^t PZH | OFD. | А | 1.3 | 4.6 | 1.3 | 1/2 | 1.3 | 5.5 | ns |
| ^t PZL | OEBA | ^ | 1 | 6.1 | 1 | 2 | 1 | 7.1 | 115 |
| ^t PHZ | OFD. | А | 2 | 6.3 | 2 | ζ | 2 | 7 | 20 |
| ^t PLZ | OEBA | A | 1.4 | 5.4 | 1.4 | | 1.4 | 5.8 | ns |
| ^t PZH | OFAR | В | 1.6 | 6.2 | 1 .6 | | 1.6 | 6.8 | |
| ^t PZL | OEAB | | 2 | 5.9 | 2 | | 2 | 6.4 | ns |
| ^t PHZ | OFAR | В | 1.2 | 5.6 | 1.2 | | 1.2 | 6.5 | |
| t _{PLZ} | OEAB | D | 1.1 | 4.7 | 1.1 | | 1.1 | 5.6 | ns |

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan | Lead finish/ Ball material | MSL Peak Temp | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|--------------|-------------------------------|--------------------|--------------|-------------------------|---------|
| SN74ABT620DW | ACTIVE | SOIC | DW | 20 | 25 | RoHS & Green | (6) NIPDAU | Level-1-260C-UNLIM | -40 to 85 | ABT620 | Samples |
| SN74ABT620N | ACTIVE | PDIP | N | 20 | 20 | RoHS & Green | NIPDAU | N / A for Pkg Type | -40 to 85 | SN74ABT620N | Samples |
| SN74ABT620NSR | ACTIVE | SOP | NS | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | ABT620 | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





| A0 | Dimension designed to accommodate the component width |
|----|---|
| В0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|-----------------|--------------------|----|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| SN74ABT620NSR | SOP | NS | 20 | 2000 | 330.0 | 24.4 | 8.4 | 13.0 | 2.5 | 12.0 | 24.0 | Q1 |

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

| | Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| Γ | SN74ABT620NSR | SOP | NS | 20 | 2000 | 367.0 | 367.0 | 45.0 |

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (µm) | B (mm) |
|--------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| SN74ABT620DW | DW | SOIC | 20 | 25 | 507 | 12.83 | 5080 | 6.6 |
| SN74ABT620N | N | PDIP | 20 | 20 | 506 | 13.97 | 11230 | 4.32 |

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